

C3S PLATFORM DATA SHEET C3S ELECTRONICS DEVELOPMENT LLC HU-1097 BUDAPEST, KÖNYVES KÁLMÁN KRT. 12-14. WWW.C3S.HU • SALES@C3S.HU • +36-21-200-5160

6U STRUCTURE

DESCRIPTION

C3S's CubeSat structures are developed to provide optimal configurability. The design is based on simple modular elements and standard attachment points. Multiple subunit architectures can be accommodated, such as: stacked PCB-, backplane-, PCB card retainer- and cable harness design. The platform includes internal separation subframes in different sizes, full off possible interfaces, if the internal volume partition, or additional interface points are needed. With these features our platform represents a fully market ready and flexible solution in terms of innovative new space approach.

- High reliability electronic, structural, and thermal connections
- Access to individual cards and units during integration and testing
- The design facilitates the easy fastening of a radiation shielding, thus the manufacturing of HiRel satellites
- Made of aluminium with ECSS standard elox coating along the rails
- Simplified stack-up tolerances
- Dedicated and independent thermal interfaces for all cards
- Optimized for high dissipation density



SPECIFICATION

1 Hysical Froperties	
Primary Structure Mass	1092g
Secondary Structure	Depending on payload
Outside envelope (mm)	100 x 226.3 x 366
Customization	
PCB stack orientation	Longitudinal (Z), Lateral (X, Y)
PCB accomodation	PC 104 USF- pattern Custom design